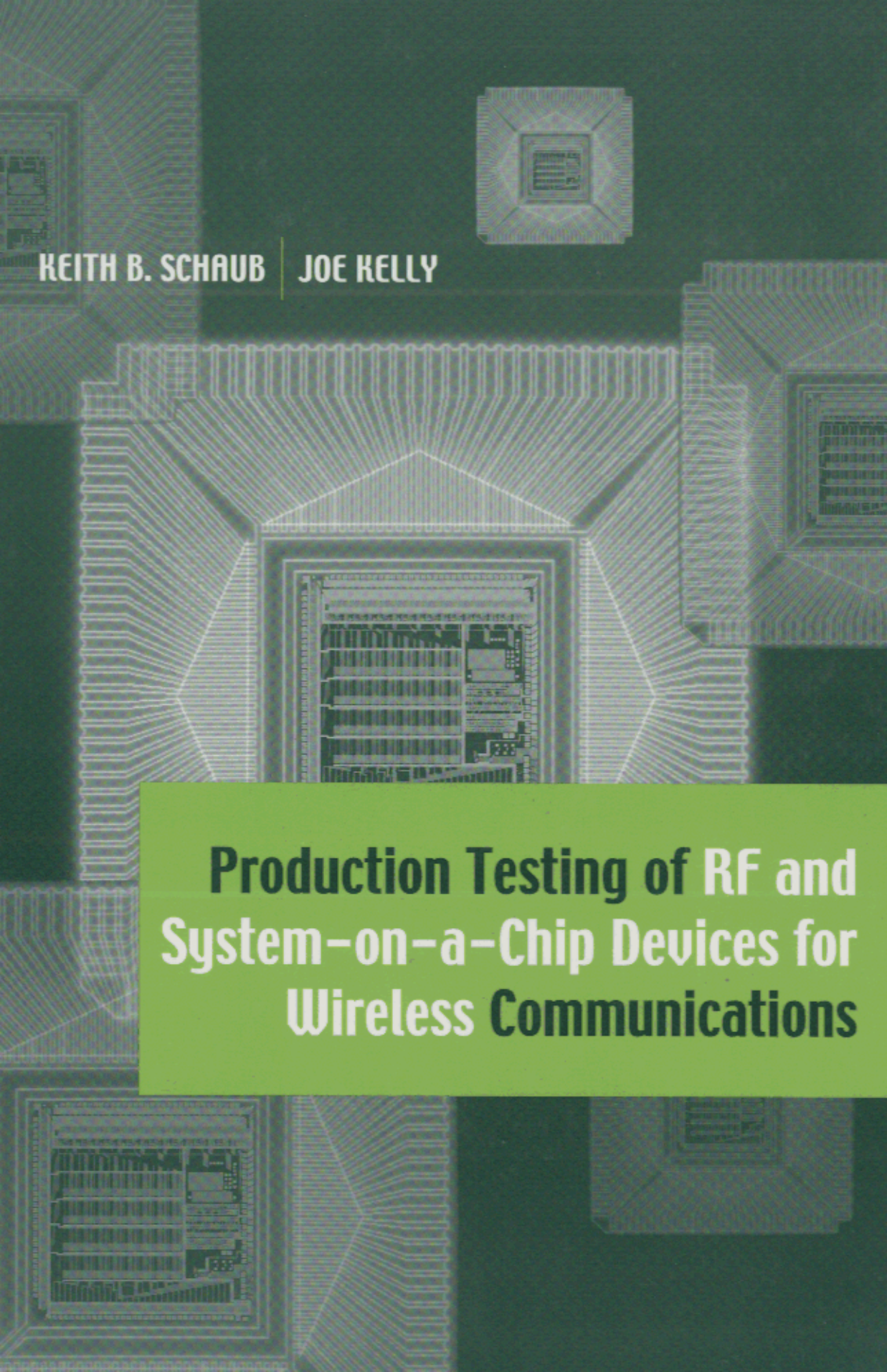


The background of the book cover is a dark green color with a faint, repeating pattern of microchip die images. The pattern is composed of several large, light-colored die shapes, each with a central square area containing a smaller square, representing the chip's internal structure and pins. The pattern is arranged in a grid-like fashion, with the die images slightly offset from each other, creating a sense of depth and repetition.

KEITH B. SCHAUB | JOE KELLY

Production Testing of RF and System-on-a-Chip Devices for Wireless Communications

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